

# RN00388

## EtherNet/IP Protocol Software Stack for Ring-Node

Rev. 3.0 — 12 December 2025

Release notes

### Document information

Information	Content
Keywords	RN00388, EtherNet/IP, protocol software stack, MIMXRT1180-EVK
Abstract	This document is the release notes for EtherNet/IP protocol software stack for ring-node. Supports: MIMXRT1180-EVK.



## 1 Features

This page lists all supported features of the EtherNet/IP protocol stack.

- Class 3 Server (connected explicit messages).
- Class 1 I/O (connected) Server (implicit messages).
- UCMM (unconnected) Server (unconnected explicit messages).
- Extensible for application and profile objects.
- Number of Explicit connections: configurable (limited by RAM).
- Number of Implicit connections: configurable (limited by RAM).
- Supported connection types: exclusive owner input only and listen only.
- IP Assignment via Dynamic Host Configuration Protocol (DHCP) or static IP address.
- Support single-port or multiport devices.
- Supported link speeds 10 Mbit/s, 100 Mbit/s, 1000 Mbit/s.
- Support LargeForwardOpen service (connections with data size > 511 bytes).
- DLR Beacon-based ring nodes are supported with a beacon period of 400  $\mu$ s.
- Address Conflict Detection (ACD) is supported for single-port and multiport devices.

**Note:** *The demo version of the software libraries has no feature restrictions, but are limited to a runtime of five hours.*

### 1.1 Objects supported by default

- Identity Object
- Message Router Object
- Assembly Object
- Connection Manager Object
- TCP/IP Object
- Ethernet Link Object
- DLR (Ring Node only)
- QoSParameter Objects

## 2 Known restrictions

Only one instance of the DLR protocol is supported, which means only two ports of a device can be used as ring ports.

**Note:** *The DLR supervisor implementation is not supported yet*

## 3 Changelog and open issues

The following is the list of the changelog and open issues.

- **Conformance test for app `04\_parameter`**
  - The conformance test for the app `04\_parameter` failed.
  - The following errors occurred during testing for instances of the Parameter class:
    - Error: Instance ID is out of sequence order – occurred four times.
    - Error: Found four instances, expected eight instances – occurred multiple times.
  - The CT tool attempted to find instances with IDs 1, 2, 3, and 4, but the app did not respond to these requests.

- For instance, ID 6, invalid settings caused two STC errors.
- The parameter section of the EDS file does not contain an entry. For instance, ID 8.
- **Simplified handling of UDP sockets for implicit connections**
  - The stack now uses a fixed number of UDP sockets for implicit connections, not a new socket for each connection.
  - This change obsoletes the function `goal_eipCfgNumImplicitConSet()`.
- **Connection event callback invoked Twice for time-out connections**
  - Previously, if an active connection timed out, the stack invoked the connection event callback twice: once for closure and once for timeout.
  - The bug fix ensures that only the event `GOAL_EIP_CONNECTION_EVENT_TIMEOUT` is raised when a connection times out.
- **ForwardOpen requests with connection points only**
  - The stack rejects ForwardOpen requests for implicit connections that contain only connection points without an instance ID.
- **ForwardOpen requests with zero-length configuration data**
  - If a ForwardOpen request includes a data segment of length 0, the stack evaluates the configuration connection point.
  - If the Assembly ID is not found, the stack rejects the request.
  - If configuration data is absent, the stack ignores the configuration connection point.
- **Configuration API typo**
  - The header file contained a typo in the function name `goal_eipCfgNumExpltitConSet()`.
  - Renamed the function to `goal_eipCfgNumExplicitConSet()` to align with the generated code.
- **Support for parameter object without config assembly**
  - If the application does not use a config assembly, parameter class attribute 9 returns the value 0.
- **CIP output assemblies are not updated with preset sequence numbers**
  - Some PLCs start implicit I/O connections with CIP sequence counters not equal to zero.
  - Due to signed/unsigned conversion issues, received I/O data with sequence counters greater than 32,767 did not trigger new-data callbacks.
  - The fix ensures proper handling of large sequence counters.
- **Closing event of IO net channels**
  - When GOAL shuts down, all Net channels close.
  - The callback handler of the IO Net channels always assumes that a data buffer is present.
  - The fix prevents null pointer access.
- **Interface configuration attributes not updated with ACD enabled**
  - The stack now correctly updates the Interface Configuration attribute when set by the application and ACD is enabled.
- **TCP server socket QoS DSCP value**
  - The TCP server socket did not apply the DSCP value in the IP header of the TCP acknowledgment frame during connection setup.
  - The fix ensures that the DSCP value is applied correctly from the start.
- **Invalid Netmask configurations**
  - The TCP/IP Interface Object previously accepted invalid Netmask values via Attribute 5.
  - The fix enforces validation for Netmask configurations.
- **Missing COS trigger type in device descriptions**
  - The EDS file lacked information about the supported COS trigger type.

- Added COS trigger type to all device descriptions.
- **CM: Proper error status for invalid ForwardOpen parameters**
  - For misconfigured multicast addresses, for example, 0.0.0.0, in the ForwardOpen requests, the device now returns the extended error status 0x0810 – NO TARGET APPLICATION DATA AVAILABLE as per ODVA specification.

## 4 Revision history

[Table 1](#) summarizes the revisions to this document.

Table 1. Revision history

Document ID	Release date	Description
RN00388 v.3.0	12 December 2025	Initial public release

## Legal information

### Definitions

**Draft** — A draft status on a document indicates that the content is still under internal review and subject to formal approval, which may result in modifications or additions. NXP Semiconductors does not give any representations or warranties as to the accuracy or completeness of information included in a draft version of a document and shall have no liability for the consequences of use of such information.

### Disclaimers

**Limited warranty and liability** — Information in this document is believed to be accurate and reliable. However, NXP Semiconductors does not give any representations or warranties, expressed or implied, as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. NXP Semiconductors takes no responsibility for the content in this document if provided by an information source outside of NXP Semiconductors.

In no event shall NXP Semiconductors be liable for any indirect, incidental, punitive, special or consequential damages (including - without limitation - lost profits, lost savings, business interruption, costs related to the removal or replacement of any products or rework charges) whether or not such damages are based on tort (including negligence), warranty, breach of contract or any other legal theory.

Notwithstanding any damages that customer might incur for any reason whatsoever, NXP Semiconductors' aggregate and cumulative liability towards customer for the products described herein shall be limited in accordance with the Terms and conditions of commercial sale of NXP Semiconductors.

**Right to make changes** — NXP Semiconductors reserves the right to make changes to information published in this document, including without limitation specifications and product descriptions, at any time and without notice. This document supersedes and replaces all information supplied prior to the publication hereof.

**Suitability for use** — NXP Semiconductors products are not designed, authorized or warranted to be suitable for use in life support, life-critical or safety-critical systems or equipment, nor in applications where failure or malfunction of an NXP Semiconductors product can reasonably be expected to result in personal injury, death or severe property or environmental damage. NXP Semiconductors and its suppliers accept no liability for inclusion and/or use of NXP Semiconductors products in such equipment or applications and therefore such inclusion and/or use is at the customer's own risk.

**Applications** — Applications that are described herein for any of these products are for illustrative purposes only. NXP Semiconductors makes no representation or warranty that such applications will be suitable for the specified use without further testing or modification.

Customers are responsible for the design and operation of their applications and products using NXP Semiconductors products, and NXP Semiconductors accepts no liability for any assistance with applications or customer product design. It is customer's sole responsibility to determine whether the NXP Semiconductors product is suitable and fit for the customer's applications and products planned, as well as for the planned application and use of customer's third party customer(s). Customers should provide appropriate design and operating safeguards to minimize the risks associated with their applications and products.

NXP Semiconductors does not accept any liability related to any default, damage, costs or problem which is based on any weakness or default in the customer's applications or products, or the application or use by customer's third party customer(s). Customer is responsible for doing all necessary testing for the customer's applications and products using NXP Semiconductors products in order to avoid a default of the applications and the products or of the application or use by customer's third party customer(s). NXP does not accept any liability in this respect.

**Terms and conditions of commercial sale** — NXP Semiconductors products are sold subject to the general terms and conditions of commercial sale, as published at <https://www.nxp.com/profile/terms>, unless otherwise agreed in a valid written individual agreement. In case an individual agreement is concluded only the terms and conditions of the respective agreement shall apply. NXP Semiconductors hereby expressly objects to applying the customer's general terms and conditions with regard to the purchase of NXP Semiconductors products by customer.

**Export control** — This document as well as the item(s) described herein may be subject to export control regulations. Export might require a prior authorization from competent authorities.

**Suitability for use in non-automotive qualified products** — Unless this document expressly states that this specific NXP Semiconductors product is automotive qualified, the product is not suitable for automotive use. It is neither qualified nor tested in accordance with automotive testing or application requirements. NXP Semiconductors accepts no liability for inclusion and/or use of non-automotive qualified products in automotive equipment or applications.

In the event that customer uses the product for design-in and use in automotive applications to automotive specifications and standards, customer (a) shall use the product without NXP Semiconductors' warranty of the product for such automotive applications, use and specifications, and (b) whenever customer uses the product for automotive applications beyond NXP Semiconductors' specifications such use shall be solely at customer's own risk, and (c) customer fully indemnifies NXP Semiconductors for any liability, damages or failed product claims resulting from customer design and use of the product for automotive applications beyond NXP Semiconductors' standard warranty and NXP Semiconductors' product specifications.

**HTML publications** — An HTML version, if available, of this document is provided as a courtesy. Definitive information is contained in the applicable document in PDF format. If there is a discrepancy between the HTML document and the PDF document, the PDF document has priority.

**Translations** — A non-English (translated) version of a document, including the legal information in that document, is for reference only. The English version shall prevail in case of any discrepancy between the translated and English versions.

**Security** — Customer understands that all NXP products may be subject to unidentified vulnerabilities or may support established security standards or specifications with known limitations. Customer is responsible for the design and operation of its applications and products throughout their lifecycles to reduce the effect of these vulnerabilities on customer's applications and products. Customer's responsibility also extends to other open and/or proprietary technologies supported by NXP products for use in customer's applications. NXP accepts no liability for any vulnerability. Customer should regularly check security updates from NXP and follow up appropriately. Customer shall select products with security features that best meet rules, regulations, and standards of the intended application and make the ultimate design decisions regarding its products and is solely responsible for compliance with all legal, regulatory, and security related requirements concerning its products, regardless of any information or support that may be provided by NXP.

NXP has a Product Security Incident Response Team (PSIRT) (reachable at [PSIRT@nxp.com](mailto:PSIRT@nxp.com)) that manages the investigation, reporting, and solution release to security vulnerabilities of NXP products.

**NXP B.V.** — NXP B.V. is not an operating company and it does not distribute or sell products.

### Trademarks

Notice: All referenced brands, product names, service names, and trademarks are the property of their respective owners.

**NXP** — wordmark and logo are trademarks of NXP B.V.

Tables

Tab. 1. Revision history .....4

Contents

1       **Features** .....2

1.1     Objects supported by default .....2

2       **Known restrictions** ..... 2

3       **Changelog and open issues** .....2

4       **Revision history** .....4

**Legal information** .....5

Please be aware that important notices concerning this document and the product(s) described herein, have been included in section 'Legal information'.